

**Preliminary Amendment**

Applicant: Min Wee Low, et al.

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Title: **NON-LEADED SEMICONDUCTOR PACKAGE AND A METHOD TO ASSEMBLE THE SAME**

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**IN THE ABSTRACT**

Please replace the Abstract with the following rewritten paragraph:

**NON-LEADED SEMICONDUCTOR PACKAGE AND A METHOD TO ASSEMBLE  
THE SAME****Abstract**

A method to assemble a non-leded semiconductor package ~~(1)~~ comprises the following steps disclosed. In one embodiment, A carrier tape ~~(13)~~ is attached to a metal foil ~~(12)~~. A plurality of leadframes ~~(3)~~ is are formed in the metal foil ~~(12)~~, each leadframe ~~(3)~~ comprising including a die pad ~~(4)~~ laterally surrounded by a plurality of contact leads ~~(5)~~. A semiconductor die ~~(2)~~, including an active surface with a plurality of die contact pads ~~(7)~~, is attached to each die attach pad ~~(4)~~ and electrically connected to the leadframe ~~(3)~~ by a plurality of bond wires ~~(6)~~ connecting the die contact pads ~~(7)~~ and the lead contact areas ~~(6)~~ of the contact leads ~~(5)~~. A plurality of leadframes ~~(3)~~, each including a wire bonded semiconductor die, are encapsulated with mold material ~~(10)~~. The carrier tape ~~(13)~~ is removed and the non-leded semiconductor packages ~~(1)~~ separated.

[Fig. 5]